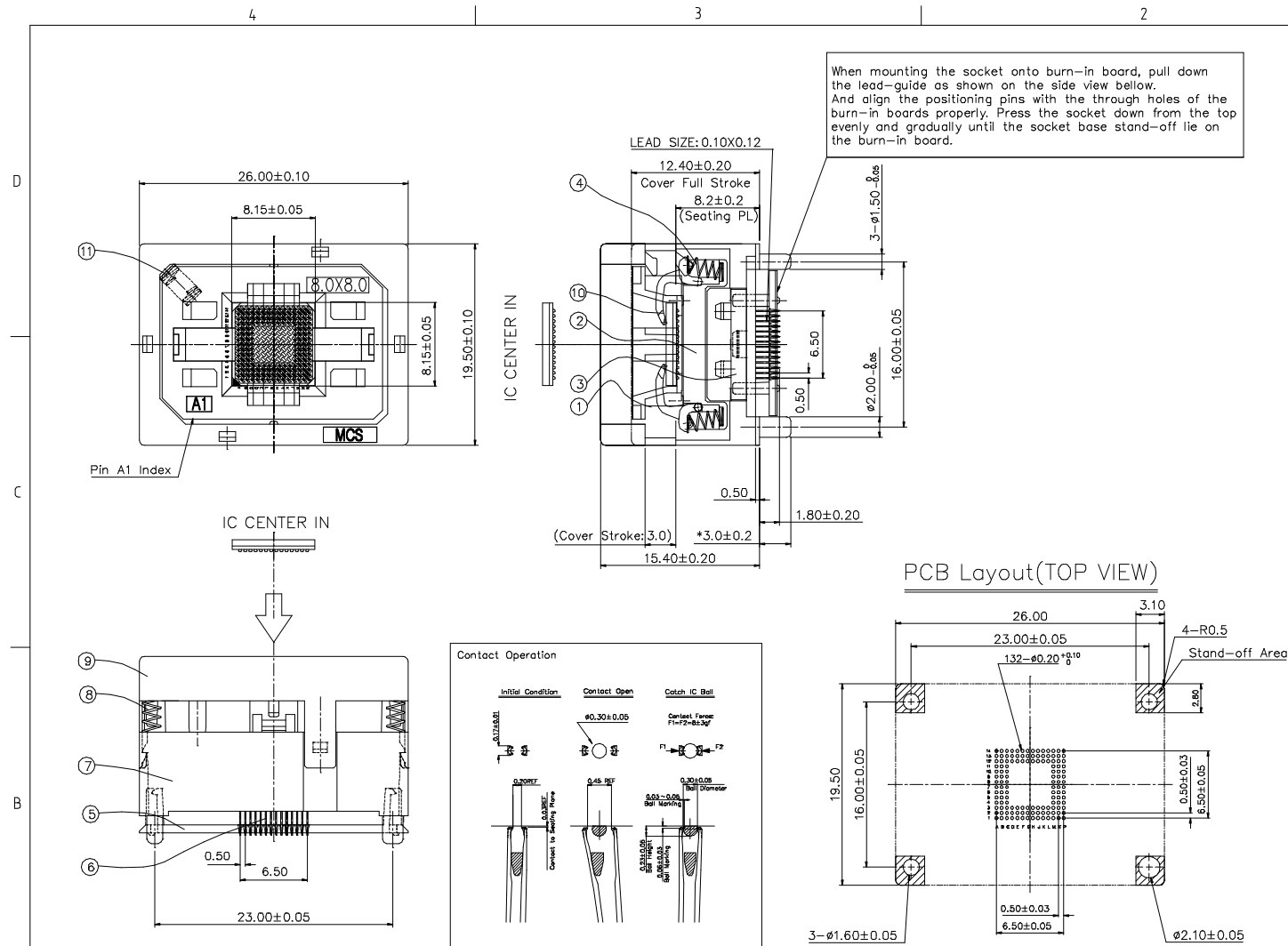




Operating Method

1. IC Inserting Operation

- (a) Push the cover all the way down(3mm) until it stops then insert the IC on top of Adapter Part NO 1.
- (b) To lock the IC in place, release up the cover .

2. IC Removing Operation

Push the cover all the way down(3mm) until it stops then take the IC out.

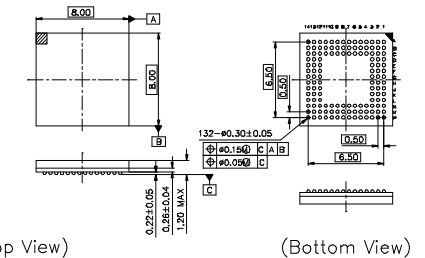
(When the cover is pushed down, a vacuum method can be used to pull out the IC.)

SPECIFICATION	
CONTACT RESISTANCE	50m Ω or less at 10mA (initial)
OPERATING TEMPERATURE	(-65℃) - (+150℃)
ACTION FORCE	Max 1.8Kg

PARTS LIST				
NO	NAME	MATERIAL	Q'TY	FINISH
1	ADAPTER	PEI(GF)	1	(Black)
2	SLIDER	PEI(GF)	1	(Black)
3	STOPPER	PEI(GF)	1	(Black)
4	LATCH SPRING	SUS	2	
5	LEAD GUIDE	PEI(GF)	1	
6	CONTACT	BeCu	132	Ni+Au
7	BASE	PEI(GF)	1	(Black)
8	COVER SPRING	SUS	4	
9	COVER	PEI(GF)	1	(Black)
10	LATCH	PEI(GF)	2	(Black)
11	SLIDER SPRING	SUS	1	

IC Dimension

132-ECSP-8.0x8.0



DRAWN 2002.04.03	DATE	DWG NO GDPHA-
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			DRAWN '02.11.22	DATE					
			DESIGNED D.W.Hwang			TITLE 0.5P-BGA Socket 132-ECSP-8.0X8.0			
REF.	NEXT ASS'Y	USED ON	CHECKED						
COMMON TOLERANCES			VERIFIED			SIZE A3	DWG NO	SB132F-HA	
NUMERIC ± 0.10		ANGLE ±	APPROVED D.W.Hwang			SCALE	NS	UNIT	mm SHEET 1 OF 1